

SGM7227 High Speed USB 2.0 (480Mbps) DPDT Analog Switch

GENERAL DESCRIPTION

The SGM7227 is a high-speed, low-power double-pole/ double-throw (DPDT) analog switch that operates from a single 1.8V to 4.3V power supply.

SGM7227 is designed for the switching of high-speed USB 2.0 signals in handset and consumer applications, such as cell phones, digital cameras, and notebooks with hubs or controllers with limited USB I/Os.

The SGM7227 has low bit-to-bit skew and high channel-to-channel noise isolation, and is compatible with various standards, such as high-speed USB 2.0 (480 Mbps). Each switch is bidirectional and offers little or no attenuation of the high-speed signals at the outputs. Its bandwidth is wide enough to pass high-speed USB 2.0 differential signals (480 Mb/s) with good signal integrity.

The SGM7227 contains special circuitry on the D+/Dpins which allows the device to withstand a V_{BUS} short to D+ or D- when the USB devices are either powered off or powered on.

SGM7227 is available in Green UTQFN1.8×1.4-10L and MSOP10 packages. It operates over an ambient temperature range of -40°C to +85°C.

APPLICATIONS

Route Signals for USB 2.0 MP3 and Other Personal Media Players Digital Cameras and Camcorders Portable Instrumentation Set-Top Box PDAs

SG Micro Limited www.sg-micro.com

FEATURES

- R_{ON} is Typically 5 Ω at 3.0V
- Voltage Operation: 1.8V to 4.3V
- Fast Switching Times: t_{ON} 15ns t_{OFF} 20ns
- Crosstalk: -30dB at 250MHz
- Off-Isolation: -35dB at 250MHz
- Rail-to-Rail Input and Output Operation
- Break-Before-Make Switching
- Extended Industrial Temperature Range: -40℃ to +85℃
- Available in Green UTQFN1.8×1.4-10L and MSOP10 Packages

BLOCK DIAGRAM



High Speed USB 2.0 (480Mbps) DPDT Analog Switch

PACKAGE/ORDERING INFORMATION

MODEL	PIN- PACKAGE	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKAGE OPTION
SGM7227	MSOP10	-40°C to +85°C	SGM7227YMS10G/TR	SGM7227YMS10	Tape and Reel, 3000
	UTQFN1.8×1.4-10L	-40°C to +85°C	SGM7227YUWQ10G/TR	7227	Tape and Reel, 3000

ABSOLUTE MAXIMUM RATINGS

V _{CC} to GND	0V to 4.6V
Analog, Digital voltage range	0.3V to (V _{CC}) + 0.3V
Continuous Current HSDn or Dn	±50mA
Peak Current HSDn or Dn	±100mA
Operating Temperature Range	40°C to +85°C
Junction Temperature	150°C

Storage Temperature	65°C to +150°C
Lead Temperature (soldering, 10s)	260°C
ESD Susceptibility	
HBM (UTQFN1.8×1.4-10L)	4000V
MM (UTQFN1.8×1.4-10L)	400V

NOTE:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

CAUTION

This integrated circuit can be damaged by ESD if you don't pay attention to ESD protection. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.



High Speed USB 2.0 (480Mbps) DPDT Analog Switch

PIN CONFIGURATIONS (TOP VIEW)





PIN DESCRIPTION

PII	N		EUNCTION	
UTQFN1.8×1.4-10L MSOP10			FUNCTION	
9	1	V _{CC}	Power Supply	
3	5	GND	Ground	
10	2	S	Select Input	
8	10	OE	Output Enable	
5	7	HSD1+	Multiplexed Source Inputs	
4	6	HSD1-	Multiplexed Source Inputs	
7	9	HSD2+	Multiplexed Source Inputs	
6	8	HSD2-	Multiplexed Source Inputs	
1	3	D+	USB Data Bus	
2	4	D-	USB Data Bus	

FUNCTION TABLE

OE	S	HSD1+, HSD1-	HSD2+, HSD2-
0	0	ON	OFF
0	1	OFF	ON
1	×	OFF	OFF

Switches Shown For Logic "0" Input



High Speed USB 2.0 (480Mbps) DPDT Analog Switch

ELECTRICAL CHARACTERISTICS

(V_{CC} = +3.3V, T_A = +25°C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
ANALOG SWITCH						
Analog I/O Voltage (HSD1+, HSD1-, HSD2+, HSD2-)	V _{IS}		0		V_{CC}	V
On-Resistance	R _{ON}	V_{CC} = 3.0V, V_{IS} = 0V to 0.4V, I _D = 8mA, Test Circuit 1		5	9	Ω
On-Resistance Match Between Channels	ΔR_{ON}	V_{CC} = 3.0V, V_{IS} = 0V to 0.4V, I _D = 8mA, Test Circuit 1		0.3	0.8	Ω
On-Resistance Flatness	R _{FLAT(ON)}	$V_{CC} = 3.0V, V_{IS} = 0V$ to 1.0V, I _D = 8mA, Test Circuit 1		1	2	Ω
Power Off Leakage Current (D+, D-)	I _{OFF}	$V_{CC} = 0V, V_D = 0V \text{ to } 3.6V, V_S, V_{\overline{OE}} = 0V \text{ or } 3.6 V$			1	μA
Increase in I_{CC} per Control Voltage	I _{CCT}	V_{CC} = 3.6V, V_{S} or $V_{\overline{OE}}$ = 2.6V			5	μA
Source Off Leakage Current	I _{HSD2(OFF)} , I _{HSD1(OFF)}	$V_{CC} = 3.6V, V_{IS} = 3.3V/0.3V, V_{D} = 0.3V/3.3V$			1	μA
Channel On Leakage Current	I _{HSD2(ON)} , I _{HSD1(ON)}	V_{CC} = 3.6V, V_{IS} = 3.3V/ 0.3V, V_{D} = 3.3V/ 0.3V or floating			1	μA
DIGITAL INPUTS						
Input High Voltage	V _{IH}		1.6			V
Input Low Voltage	VIL				0.5	V
Input Leakage Current	l _{iN}	V_{CC} = 3.0V, V_S , $V_{\overline{\text{OE}}}$ = 0V or V_{CC}			1	μA
DYNAMIC CHARACTERISTICS						
Turn-On Time	t _{ON}	$V_{IS} = 0.8V, R_L = 50\Omega, C_L = 10pF,$		15		ns
Turn-Off Time	t _{OFF}	Test Circuit 2		20		ns
Break-Before-Make Time Delay	t _D	V_{IS} = 0.8V, R_L = 50 Ω , C_L = 10pF, Test Circuit 3		3.5		ns
Propagation Delay	t _{PD}	$R_L = 50\Omega$, $C_L = 10pF$		0.5		ns
Off Isolation	O _{ISO}	Signal = 0dBm, $R_L = 50\Omega$, f = 250MHz, Test Circuit 4		-35		dB
Channel-to-Channel Crosstalk	X _{TALK}	Signal = 0dBm, $R_L = 50\Omega$, f = 250MHz, Test Circuit 5		-30		dB
–3dB Bandwidth	BW	Signal = 0dBm, $R_L = 50\Omega$, $C_L = 5pF$, Test Circuit 6		550		MHz
Channel-to-Channel Skew	t _{skew}	$R_{L} = 50\Omega, C_{L} = 10pF$		130		ps
Charge Injection Select Input to Common I/O	Q	V_G = GND, C_L = 1.0nF, R_G = 0 Ω , Q = $C_L \times V_{OUT}$, Test Circuit 7		10		pC
HSD+, HSD-, D+, D- ON Capacitance	C _{ON} f	f = 1MHz		6.5		ъĘ
		f = 250MHz		7		ρr
POWER REQUIREMENTS						
Power Supply Range	V _{CC}		1.8		4.3	V
Power Supply Current	Icc	V_{CC} = 3.0V, V_{S} , $V_{\overline{\text{OE}}}$ = 0V or V_{CC}			1	μA

Specifications subject to changes without notice.



High Speed USB 2.0 (480Mbps) DPDT Analog Switch

TYPICAL PERFORMANCE CHARACTERISTICS







High Speed USB 2.0 (480Mbps) DPDT Analog Switch

TEST CIRCUITS



Test Circuit 1. On Resistance



Test Circuit 2. Switching Times (t_{ON} , t_{OFF})







TEST CIRCUITS (Cont.)



Test Circuit 4. Off Isolation



Test Circuit 5. Channel-to-Channel Crosstalk



TEST CIRCUITS (Cont.)



Test Circuit 6. -3dB Bandwidth







APPLICATION NOTES

Meeting USB 2.0 V_{BUS} Short Requirements

Power-Off Protection

For a V_{BUS} short circuit the switch is expected to withstand such a condition for at least 24 hours. The SGM7227 has specially designed circuitry which prevents unintended signal bleed through as well as guaranteed system reliability during a power-down, over-voltage condition. The protection has been added to the common pins (D+, D-).

Power-On Protection

The USB 2.0 specification also notes that the USB device should be capable of withstanding a V_{BUS} short during transmission of data. This modification works by limiting current flow back into the V_{CC} rail during the over-voltage event so current remains within the safe operating range.



SGM7227 USB2.0 Signal Quality Compliance Test Results

Figures 1 and 2 show the test results for USB eye diagram tests.



Figure 1. Waveform Plot



Figure 2. High Speed Signal Quality Eye Diagram Test (V+ = 3.3V)



High Speed USB 2.0 (480Mbps) DPDT Analog Switch

The following is a summary of the USB test Results. The SGM7227 passes the high speed signal quality, eye diagram and jitter tests.

Required Tests

- Overall result: Pass!
- Signal eye: Eye passes
- EOP width: 7.91 bits EOP width passes
- Measured signaling rate: 480.0551 MHz Signal rate passes
- Rising Edge Rate: 901.28 V/us (710.10 ps equivalent risetime)
 Passes
- Falling Edge Rate: 889.18 V/us (719.77 ps equivalent risetime) Passes

Additional Information

Consecutive jitter range: -61.770 ps to 39.668 ps, RMS jitter 21.900 ps Paired JK jitter range: -47.800 ps to 42.890 ps, RMS jitter 21.591 ps Paired KJ jitter range: -50.590 ps to 49.704 ps, RMS jitter 23.281 ps



PACKAGE OUTLINE DIMENSIONS

MSOP10





Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
A	0.820	1.100	0.032	0.043	
A1	0.020	0.150	0.001	0.006	
A2	0.750	0.950	0.030	0.037	
b	0.180	0.280	0.007	0.011	
С	0.090	0.230	0.004	0.009	
D	2.900	3.100	0.114	0.122	
E	2.900	3.100	0.114	0.122	
E1	4.750	5.050	0.187	0.199	
е	0.500 BSC		0.020 BSC		
L	0.400	0.800	0.016	0.031	
θ	0°	6°	0°	6°	

A1

A2



High Speed USB 2.0 (480Mbps) DPDT Analog Switch

PACKAGE OUTLINE DIMENSIONS

UTQFN1.8×1.4-10L



NOTE: All linear dimensions are in millimeters.

REV. A

SGMICRO is dedicated to provide high quality and high performance analog IC products to customers. All SGMICRO products meet the highest industry standards with strict and comprehensive test and quality control systems to achieve world-class consistency and reliability.

For more information regarding SGMICRO Corporation and its products, please visit www.sg-micro.com



X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Analogue Switch ICs category:

Click to view products by SGMICRO manufacturer:

Other Similar products are found below :

FSA3051TMX NLAS4684FCTCG NLAS5223BLMNR2G NLVAS4599DTT1G NLX2G66DMUTCG NS5A4684SMNTAG 425541DB 425528R 099044FB MAX4762ETB+ NLAS5123MNR2G NLAS5213AMUTAG NLAS5213AUSG PI5A4157CEX PI5A4599BCEX NLAS4717EPFCT1G PI5A3167CCEX SLAS3158MNR2G PI5A392AQEX PI5A392AQE FSA634UCX ADG714BCPZ-REEL7 HT4051ARZ TC4066BP(N,F) TMUX136RSER DG302BDJ-E3 ADG854BCPZ-REEL7 PI5A100WE PI5A100QEX HV2733FG-G HV2701FG-G HV2301FG-G HV2301FG-G-M931 RS2117YUTQK10 RS2118YUTQK10 RS2227XUTQK10 ADG452BRZ-REEL7 MAX4715EXK+T MAX391CPE+ MAX4744ELB+ MAX4730EXT+T MAX4730ELT+ MAX333AEWP+ BU4066BC MAX313CPE+ BU4866G2-TR NLAS52231MUR2G NLASB3157MTR2G TS3A4751PWR NX3L4684TK,115